Filename: PMP7148 REV_A_bom.xls

Date: 06/15/2012

PMP7148 REV_A BOM

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C1	47uF	Capacitor, Aluminum Electrolytic, 450V	0.571 inch	EKXJ451ESS470ML25S	Nippon Chemi-Con
1	C2	1000uF	Capacitor, Aluminum Electrolytic, 35V	0.492 inch	35V ZL 1000uF 12.5 X 25	Rubycon
1	C3	4.7uF	Capacitor, Ceramic, 50V, X7R, 20%	1210	GRM32ER71H475KA88L	Murata
1	C6	0.01uF	Capacitor, Ceramic, 630V, C0G, 10%	1206	C3216CH2J103K	TDK
1	C7	22uF	Capacitor, Ceramic, 16V, X7R, 20%	1210	C3225X7R1C226MT	TDK
1	C9	27uF	Capacitor, Aluminum Electrolytic, 25V	0.200 * 0.435 inch	25V ZL 27uF 5 X 11	Panasonic
1	C12	0.047uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H473K	TDK
1	C15	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H104K	TDK
1	C16	0.01uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H103K	TDK
1	C18	0.01uF	CAP, CERM DISC, 250Vac, 20%	.500 X .310	ECKATS103MF6	Panasonic
1	C19	27uF	Capacitor, Aluminum Electrolytic, 25V	0.200 * 0.435 inch	25V ZL 27uF 5 X 11	Rubycon
2	C10 C13	1uF	Capacitor, Ceramic, 16V, X7R, 20%	0603	C1608X7R1C105M	TDK
3	C11 C14 C17	100pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H101K	TDK
2	C4-5	0.1uF	Capacitor, Film, MKP 338 X2, 275VAC, 20%	.470x.250 inch	2222 338 20104	BC Components
1	D1	ES3D	Diode, 3A, 200V	SMC	ES3D-13-F	Diodes Inc.
1	D2	RH06-T	Diode, Bridge, 0.5-A, 600-V	MiniDIP	RH06-T	Diodes
1	D3	US1K	Diode Ultrafast, 1-A, 800-V	SMA	US1K	Diodes Inc.
1	D4	B160-13	Diode, Schottky, 1-A, 60-V	SMA	B160-13	Diodes Inc.
1	D5	BAS20	Diode, Switching, 150V, 200mA	SOT23	BAS20LT1	On Semiconductor
2	D6-7	BAS16	Diode, Switching, 75V, 200mA	SOT23	BAS16LT1	On Semiconductor
1	F1	2A/250V	Fuse, TR5 Series, 2A, 250V	0.335	3701200041	Littlefuse
2	J1-2	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED1514	OST
1	L1	10mH	Inductor, Common-Mode, 0.25A	0.906 x 0.748 inch	UU9.8V-103	GCI
1	Q1	IRFBC30A	MOSFET, N-ch, 600-V, 3.6-A, 2.2-Ohms	TO-220V	IRFBC30A	International Rectifier
1	R3	100k	Resistor, Chip, 1W, 5%	2512	STD	STD
1	R6	499k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R7	210k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R8	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R12	41.2k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R13	15k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R15	1k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R16	0.36	Resistor, Chip, 1/4W, 5%	1210	Std	Std
1	R17	1.15k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R18	100k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
3	R1 R5 R19	10	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R100	357k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R101	110k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R11 R14	10k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R2 R4	499k	Resistor, Chip, 1/4W, 5%	1210	Std	Std
2	R9-10	4.99k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	RT1	20 Ohms	Thermistor, NTC, 20 Ohms	0.394 inch.	B57236S200M	Epcos
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1	T1	SRW2425EG-U05V015	Transformer, Custom, Flyback	1.004 x 1.181 inch	SRW2425EG-U05V015	TDK
5	TP1-2 TP4-5 TP7	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
2	TP3 TP6	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	U1	UCC28600D	IC, Quasi-Resonant Flyback Green Mode Controller	SO8	UCC28600D	Texas Instruments
1	U2	H11A817AS	IC, Optocoupler, 5300-V, 50-160% CTR	0.435 x 0.210 inch	H11A817AS	Fairchild
1	U3	TL431AIDBZ	IC, Precision Adjustable Shunt Regulator	SOT23-3	TL431AIDBZ	Texas Instruments
1	U4	TPS77601D	IC, Fast Transient Response, 0.5-A LDO Voltage Regulator	SO8	TPS77601D	TI

- Notes: 1. These assemblies are ESD sensitive, ESD precautions shall be observed.
 - 2. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
 - 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 - 4. Ref designators marked with an asterisk ('**') cannot be substituted. All other components can be substituted with equivalent MFG's components.

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